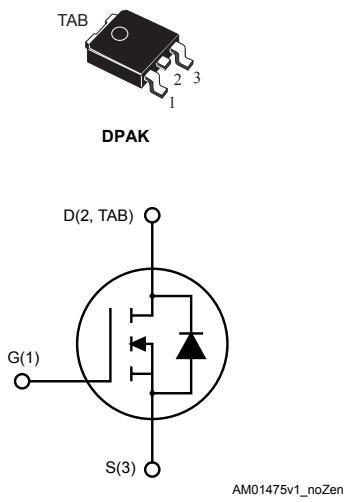


N-channel 200 V, 290 mΩ typ., 7 A, STripFET™ Power MOSFET in a DPAK package

Features



Order code	V _{DS}	R _{DSON} max.	I _D
STD7NS20T4	200 V	400 mΩ	7 A

- Extremely high dv/dt capability
- Very low intrinsic capacitance
- Gate charge minimized

Applications

- Switching applications

Description

This Power MOSFET series realized with STMicroelectronics unique STripFET™ process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency isolated DC-DC converters.



Product status link

[STD7NS20T4](#)

Product summary

Order code	STD7NS20T4
Marking	D7NS20
Package	DPAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-source voltage ($V_{GS} = 0$ V)	200	V
V_{DGR}	Drain-gate voltage ($R_{GS} = 20$ k Ω)	200	V
V_{GS}	Gate-source voltage	± 20	V
I_D	Drain current (continuous) at $T_C = 25$ °C	7	A
	Drain current (continuous) at $T_C = 100$ °C	4.4	A
$I_{DM}^{(1)}$	Drain current (pulsed)	28	A
P_{TOT}	Total power dissipation at $T_C = 25$ °C	86	W
$E_{AS}^{(2)}$	Single pulse avalanche energy	110	mJ
$dv/dt^{(3)}$	Drain-body diode dynamic dv/dt ruggedness	5.8	V/ns
T_{stg}	Storage temperature range	-65 to 175	°C
T_J	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2. Starting $T_J = 25$ °C, $I_D = 4.5$ A
3. $I_{SD} = 7$ A, $di/dt = 520$ A/ μ s, $V_{DD} = 50$ V, $T_J < T_{Jmax}$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.74	°C/W
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50	°C/W

1. When mounted on an 1-inch² FR-4, 2 Oz copper board.

2 Electrical characteristics

$T_{CASE} = 25^\circ\text{C}$ unless otherwise specified

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	200			V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V},$ $T_C = 125^\circ\text{C}$ ⁽¹⁾			100	μA
I_{GSS}	Gate body leakage current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			± 100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}$		290	400	$\text{m}\Omega$

1. Defined by design, not subject to production test.

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0 \text{ V}$	-	370	-	pF
C_{oss}	Output capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0 \text{ V}$	-	77	-	pF
C_{rss}	Reverse transfer capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0 \text{ V}$	-	14	-	pF
Q_g	Total gate charge	$V_{DD} = 160 \text{ V}, I_D = 7 \text{ A}$	-	11.6	-	nC
Q_{gs}	Gate-source charge	$V_{GS} = 0 \text{ to } 10 \text{ V}$	-	2.2	-	nC
Q_{gd}	Gate-drain charge	(see Figure 13. Test circuit for gate charge behavior)	-	5.4	-	nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 100 \text{ V}, I_D = 4.5 \text{ A},$ $R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	5.6	-	ns
t_r	Rise time	(see Figure 12. Test circuit for resistive load switching times and Figure 17. Switching time waveform)	-	2.6	-	ns

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 7 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 7 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$	-	118.5		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 50 \text{ V}$	-	393		nC
I_{RRM}	Reverse recovery current	(see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	6.6		A

1. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

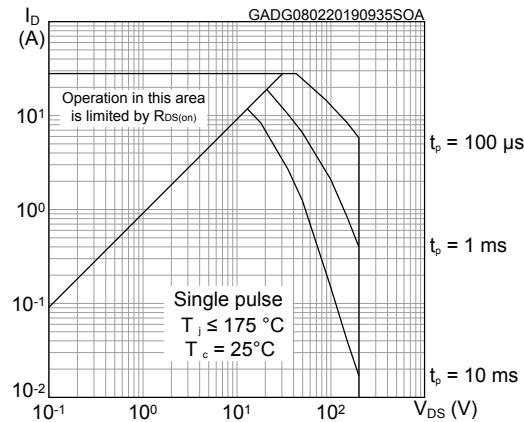


Figure 2. Thermal impedance

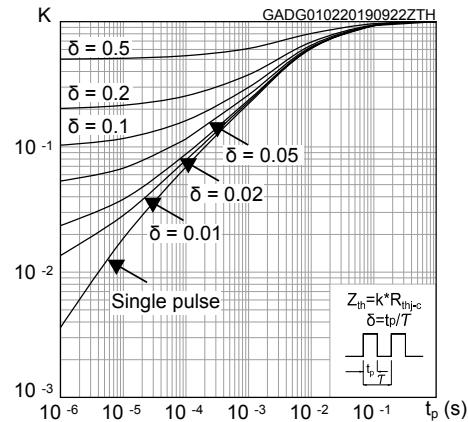


Figure 3. Output characteristics

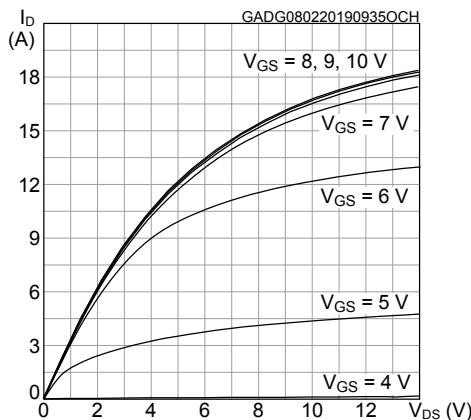


Figure 4. Transfer characteristics

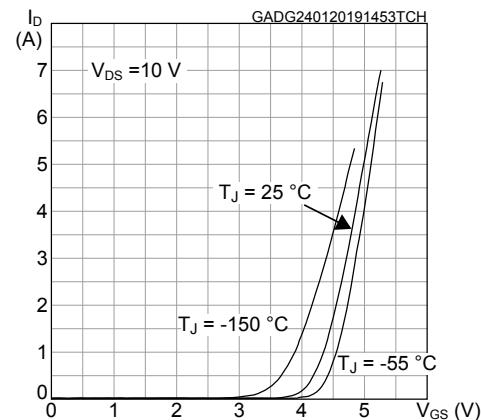


Figure 5. Gate charge vs gate-source voltage

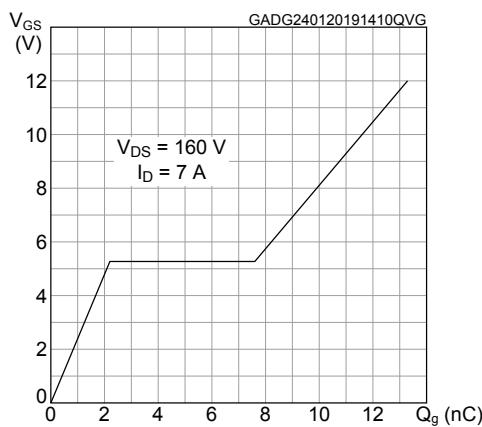


Figure 6. Static drain-source on-resistance

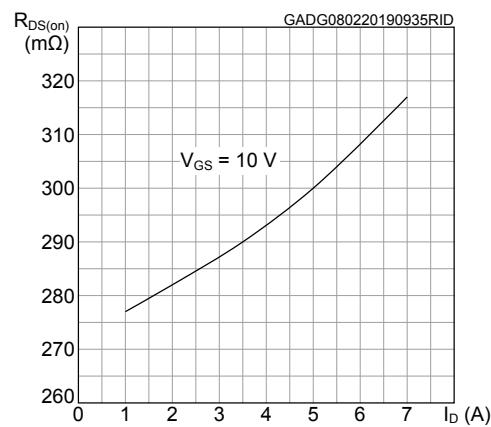
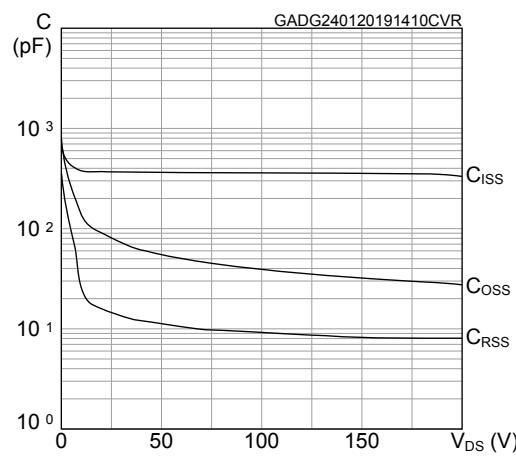
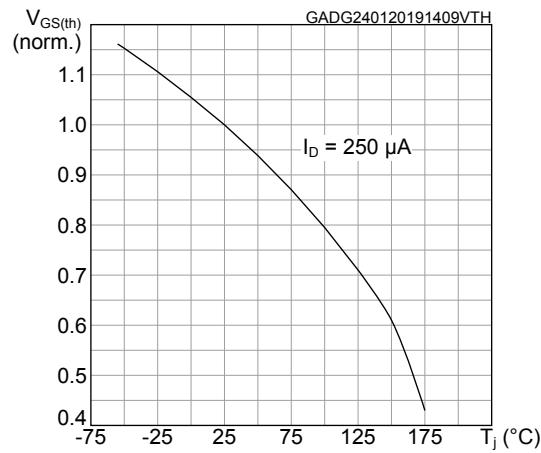
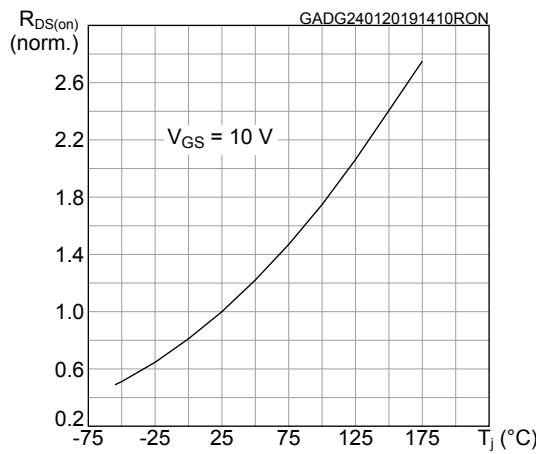
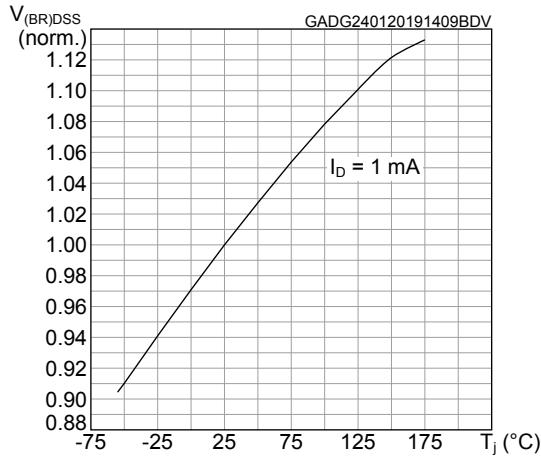
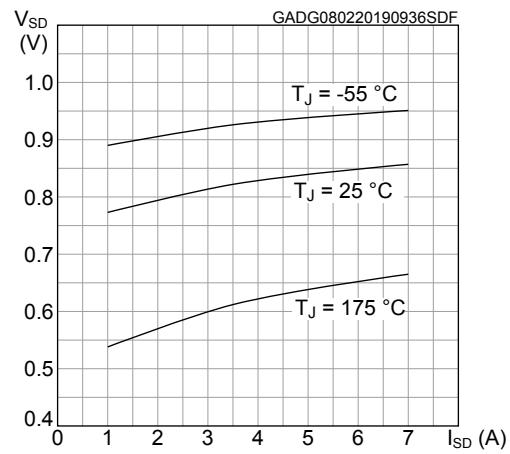
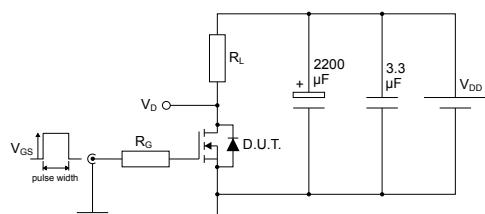


Figure 7. Capacitance variations**Figure 8. Normalized gate threshold voltage vs temperature****Figure 9. Normalized on-resistance vs temperature****Figure 10. Normalized V_{(BR)DSS} vs temperature****Figure 11. Source-drain diode forward characteristics**

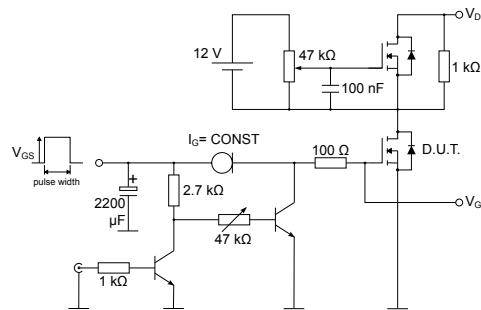
3 Test circuits

Figure 12. Test circuit for resistive load switching times



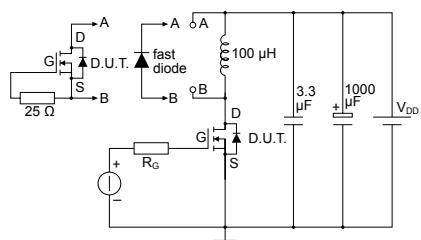
AM01468v1

Figure 13. Test circuit for gate charge behavior



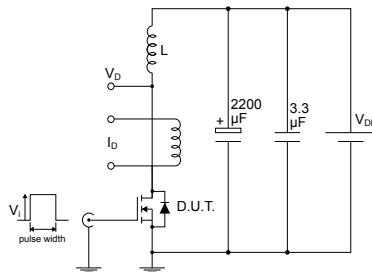
AM01469v1

Figure 14. Test circuit for inductive load switching and diode recovery times



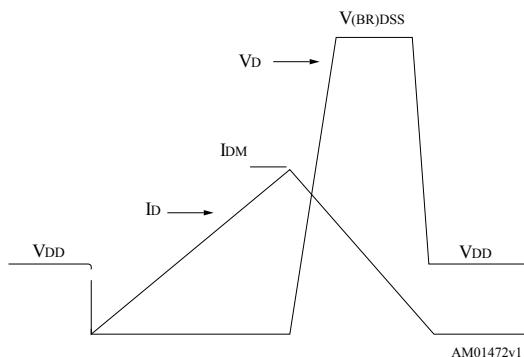
AM01470v1

Figure 15. Unclamped inductive load test circuit



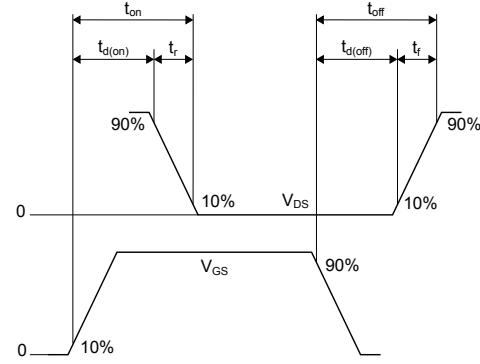
AM01471v1

Figure 16. Unclamped inductive waveform



AM01472v1

Figure 17. Switching time waveform



AM01473v1

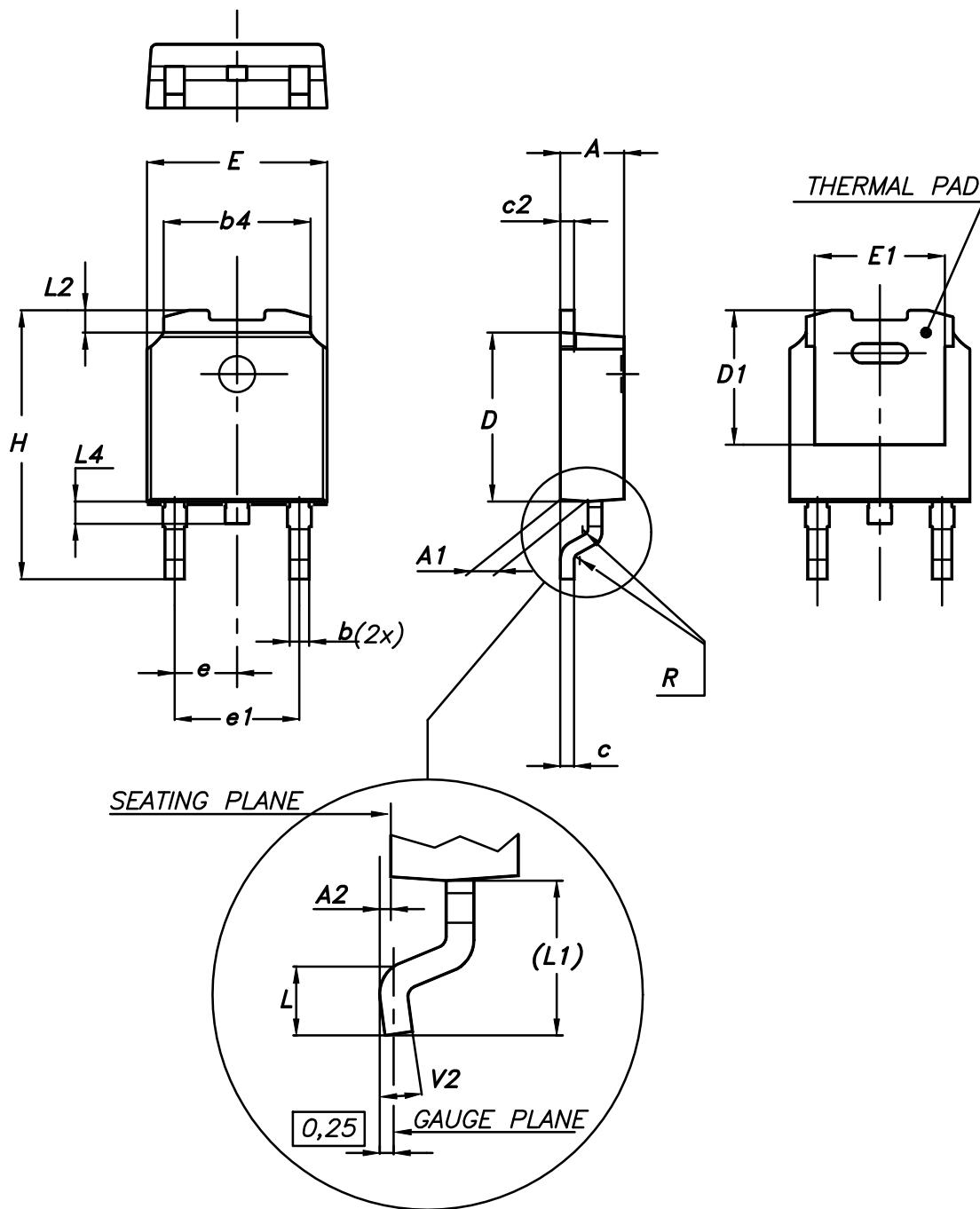
4

Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A package information

Figure 18. DPAK (TO-252) type A package outline

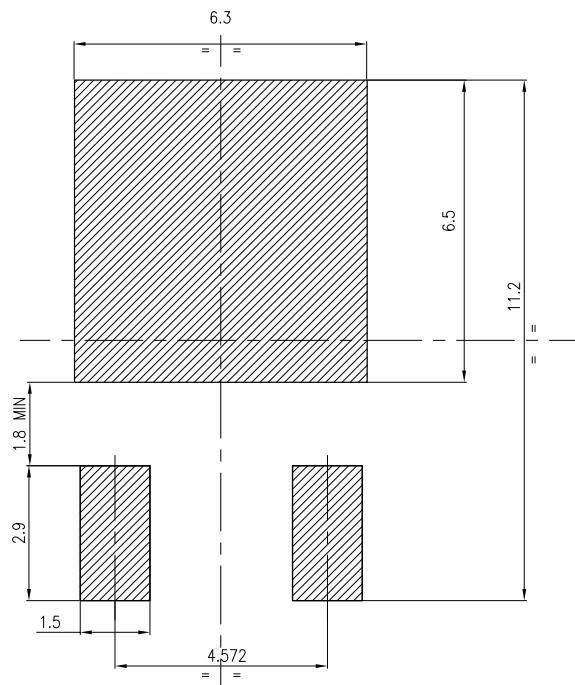


0068772_A_26

Table 7. DPAK (TO-252) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

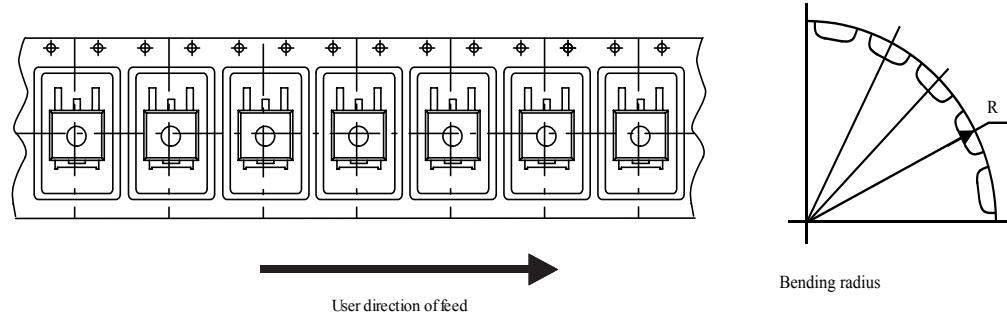
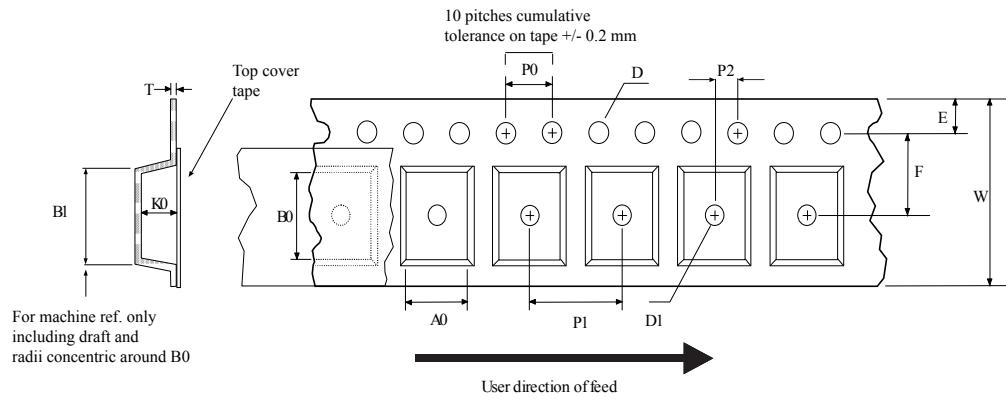
Figure 19. DPAK (TO-252) type A recommended footprint (dimensions are in mm)



FP_0068772_26

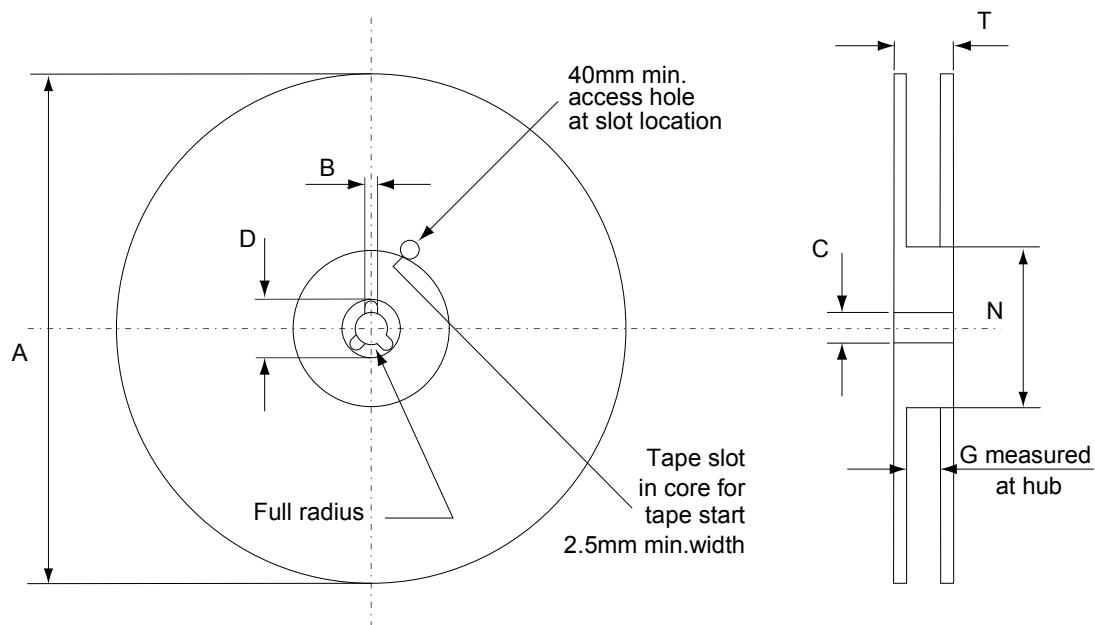
4.2 DPAK (TO-252) packing information

Figure 20. DPAK (TO-252) tape outline



Bending radius

AM08852v1

Figure 21. DPAK (TO-252) reel outline

AM06038v1

Table 8. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Revision history

Table 9. Document revision history

Date	Version	Changes
11-Feb-2019	1	First release.

Contents

1	Electrical ratings	2
2	Electrical characteristics.....	3
2.1	Electrical characteristics (curves)	5
3	Test circuits	7
4	Package information.....	8
4.1	DPAK (TO-252) type A package information	8
4.2	DPAK (TO-252) packing information.....	11
	Revision history	14

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2019 STMicroelectronics – All rights reserved

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by STMicroelectronics manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [IRFD120](#) [JANTX2N5237](#) [FCA20N60_F109](#) [FDZ595PZ](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#) [TPCC8103,L1Q\(CM](#)
[MIC4420CM-TR](#) [VN1206L](#) [SBVS138LT1G](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [SSM6J414TU,LF\(T](#) [751625C](#) [BUK954R8-60E](#)
[DMN3404LQ-7](#) [NTE6400](#) [SQJ402EP-T1-GE3](#) [2SK2614\(TE16L1,Q\)](#) [2N7002KW-FAI](#) [DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [ECH8691-](#)
[TL-W](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE221](#) [NTE2384](#) [NTE2903](#) [NTE2941](#) [NTE2945](#) [NTE2946](#) [NTE2960](#)
[NTE2967](#) [NTE2969](#) [NTE2976](#) [NTE455](#) [NTE6400A](#) [NTE2910](#) [NTE2916](#) [NTE2956](#) [NTE2911](#) [DMN2080UCB4-7](#) [TK10A80W,S4X\(S](#)
[SSM6P69NU,LF](#) [DMP22D4UFO-7B](#)